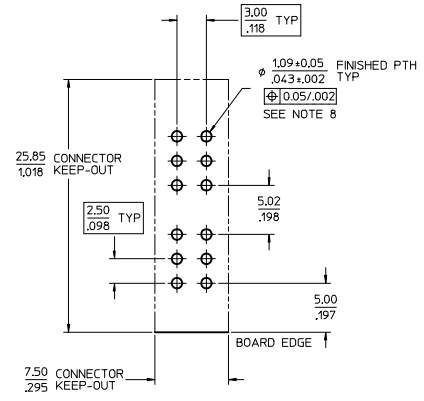
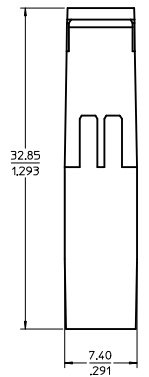
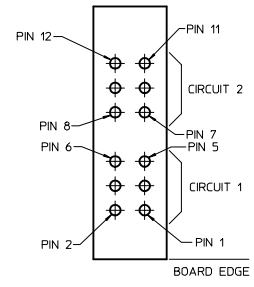


PART NUMBER	TAIL PLATING	PLATING
75561-6000	TIN	0.75µm/30µm MIN SELECT HARD GOLD IN CONTACT AREA WITH 2.50µm/100µm MIN SELECT TIN IN TAIL AREA OVER 1.25µm/50µm MIN NICKEL OVERALL

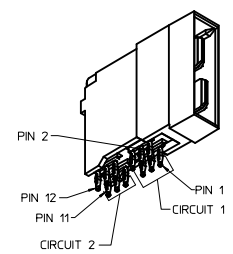
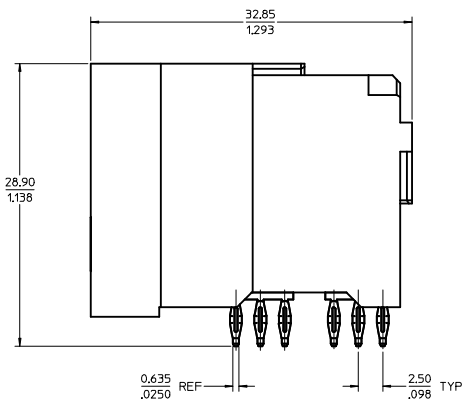
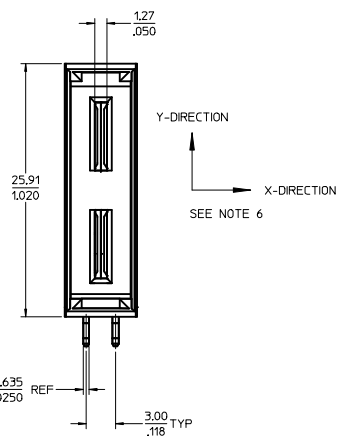
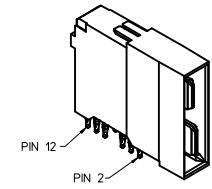


PCB LAYOUT
3.18/.125 MIN THICK



PINOUT DETAIL

- NOTES:
- MATERIALS:
 - HOUSING: 30% GLASS FILLED, LCP 94V-0, COLOR: BLACK
 - TERMINALS: COPPER ALLOY
 - PLATING: PER ES-88 - SEE CHART
 - SEE CHART FOR REFERENCE DOCUMENTS
 - PLUG MATES WITH RECEPTACLE ASSEMBLIES: 75545-5000 & 75545-5001
 - MODULE IS DESIGNED FOR PRESS FIT TO THE PCB
 - MODULE ASSEMBLY IS RoHS COMPLIANT
 - GATHERABILITY: ±0.65/.026 X-DIRECTION ±130/.051 Y-DIRECTION
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002
 - PLATED THRU HOLE (PTH) DIMENSIONS:
 - Ø1.09±0.05/Ø43±.002 FINISHED PTH (TYP)
 - Ø1.200±0.013/Ø472±.0005 DRILL
 - 0.025/.001 COPPER PLATE THICKNESS



REFERENCE DOCUMENTS	
PS-75431-999	PRODUCT SPECIFICATION: PERFORMANCE AND RATINGS
SD-75555-***	FINAL ASSEMBLY CONFIGURATION DRAWING

CORRECTED HSG GRAPHICS IEC NO: UCP2014-2193 DRAWN: DUILLES 2013/11/18 CHKD: BANDURA 2013/11/19 APPR: APATEL 2013/12/10	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	∇=0 ∇=0 ∇=0	mm INCH 4 PLACES ±.--- ±.--- 3 PLACES ±.--- ±.008 2 PLACES ±0.20 ±.013 1 PLACE ±0.33 ±.--- 0 PLACE ± ±	MM/IN	4:1	METRIC	BANDURA 2007/01/16 MDATA 2007/01/16
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-75561-200	TITLE POWERMASS 80 AMP MODULE, PLUG		SHEET NO. 1 OF 1
	SIZE D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				